

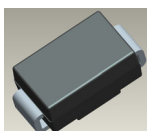
Features

- Ultra Low Forward Voltage Drop
- Excellent High Temperature Capability
- Patented Super Barrier Rectifier Technology
- Soft, Fast Switching Capability
- 175°C Operating Junction Temperature
- **Lead-Free Finish; RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**

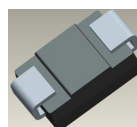
Mechanical Data

- Case: SMA
- Case Material: Molded Plastic, UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: Lead Free Plating (Matte Tin Finish.) Solderable per MIL-STD-202, Method 208 
- Polarity Indicator: Cathode Band
- Weight: 0.064 grams (approximate)

SMA



Top View



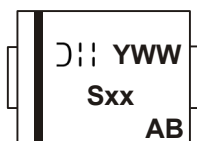
Bottom View

Ordering Information (Note 4)

Part Number	Case	Packaging
SBR2U150SA-13	SMA	5000/Tape & Reel

- Notes:
1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

Marking Information



S D B or S Q B = Product Type Marking Code
 ⑆ = Manufacturers' code marking
 YWW = Date Code Marking
 Y = Last digit of year (ex: 9 for 2009)
 WW = Week code (01 – 53)
 AB = Foundry and Assembly Code

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.
 For capacitance load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V _{RRM}	150	V
Working Peak Reverse Voltage	V _{RWM}		
DC Blocking Voltage	V _{RM}		
Average Rectified Output Current (See Figure 1)	I _O	2.0	A
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I _{FSM}	42	A
Maximum Voltage Rate of Change (Rated V _R)	dv/dt	10,000	V/μs

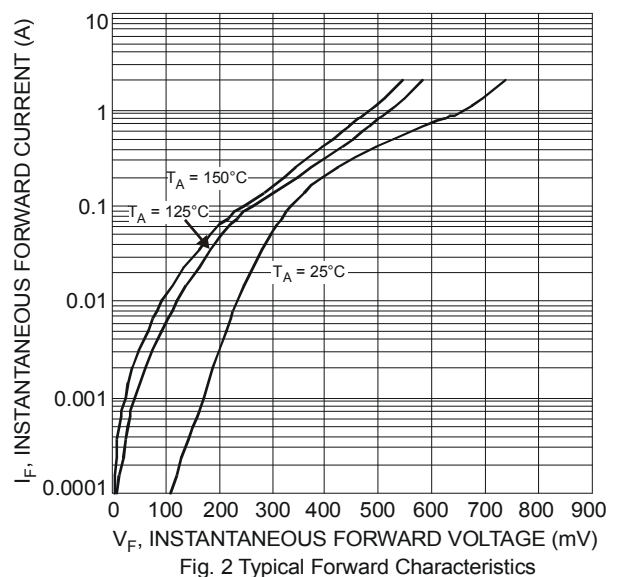
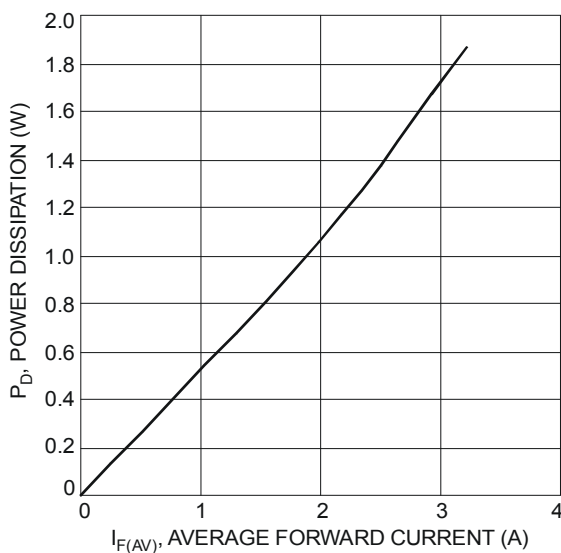
Thermal Characteristics

Characteristic	Symbol	Value	Unit
Thermal Resistance Junction to Soldering (Note 4)	R _{θJS}	3	°C/W
Thermal Resistance Junction to Ambient (Note 5)	R _{θJA}	119	
Thermal Resistance Junction to Ambient (Note 6)	R _{θJA}	88	
Operating and Storage Temperature Range	T _J , T _{STG}	-65 to +175	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 7)	V _{(BR)R}	150	—	—	V	I _R = 100μA
Forward Voltage Drop	V _F	—	—	0.8	V	I _F = 2.0A, T _J = +25°C
		—	—	0.65		I _F = 2.0A, T _J = +125°C
Leakage Current (Note 6)	I _R	—	—	75	μA	V _R = 150V, T _J = +25°C
		—	—	10	mA	V _R = 150V, T _J = +125°C

Notes: 4. Theoretical R_{θJS} calculated from the top center of the die straight down to the PCB cathode tab solder junction.
 5. FR-4 PCB, 2 oz. Copper, minimum recommended pad layout per <http://www.diodes.com>. T_A = 25°C
 6. Polyimide PCB, 2 oz. Copper, minimum recommended pad layout per <http://www.diodes.com>
 7. Short duration pulse test used to minimize self-heating effect.



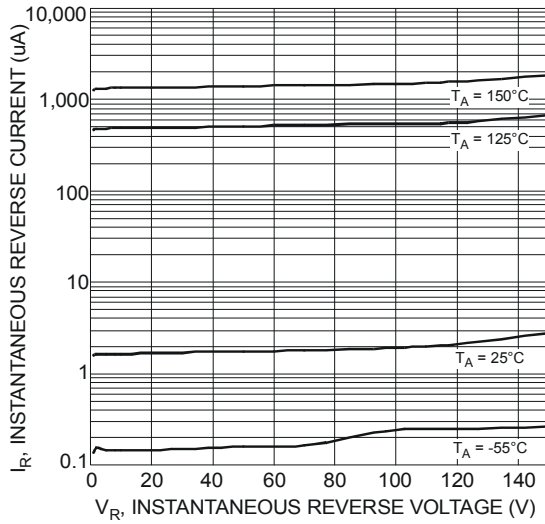


Fig. 3 Typical Reverse Characteristics

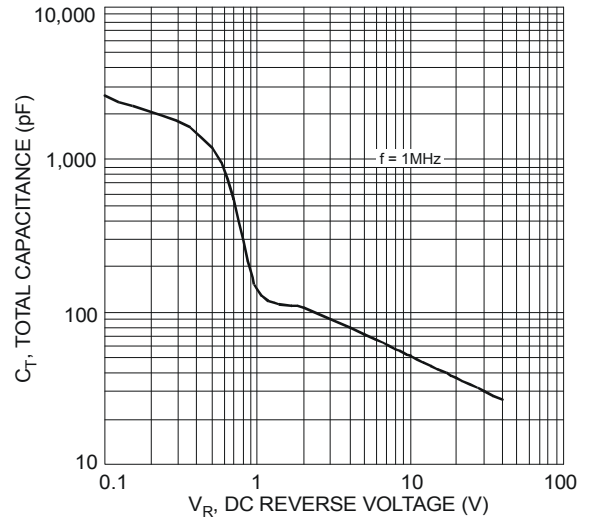


Fig. 4 Total Capacitance vs. Reverse Voltage

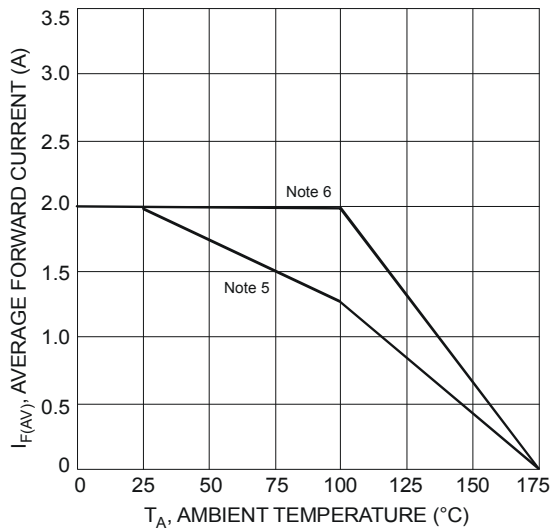


Fig. 5 DC Forward Current Derating Curve

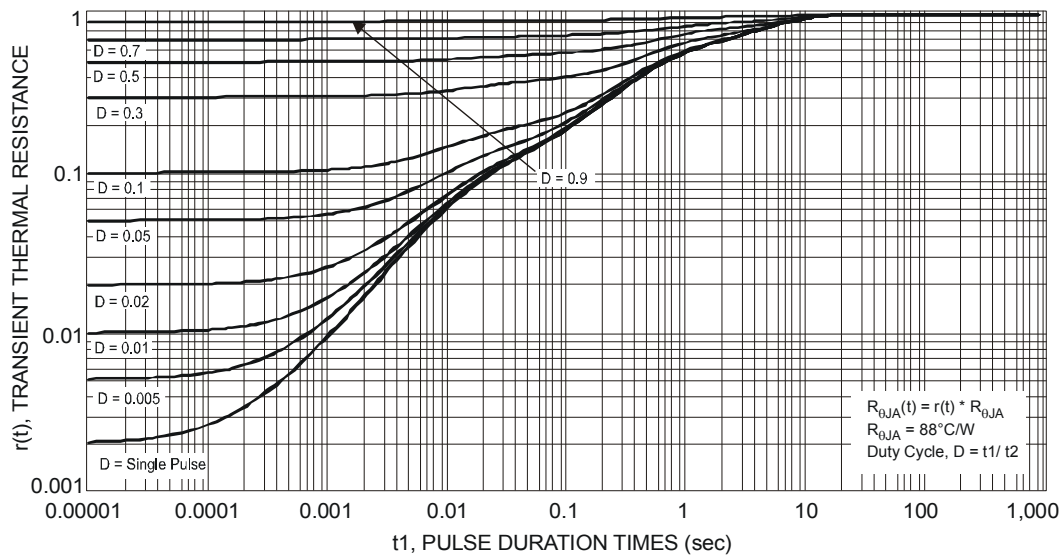
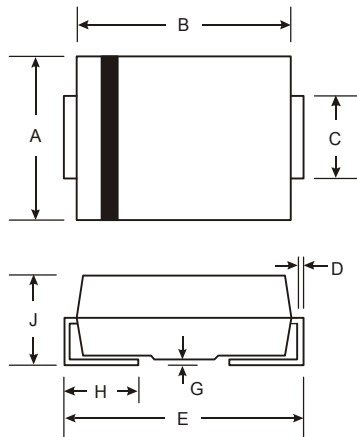


Fig. 6 Transient Thermal Resistance

Package Outline Dimensions

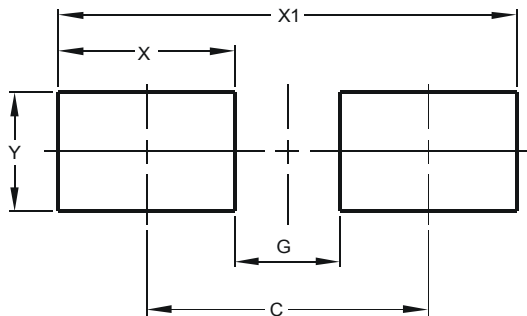
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for latest version.



SMA		
Dim	Min	Max
A	2.29	2.92
B	4.00	4.60
C	1.27	1.63
D	0.15	0.31
E	4.80	5.59
G	0.05	0.20
H	0.76	1.52
J	2.01	2.30
All Dimensions in mm		

Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
C	4.00
G	1.50
X	2.50
X1	6.50
Y	1.70

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